Reg.	No
Reg.	140

B.TECH. DEGREE EXAMINATION, MAY 2015

Seventh Semester

Branch: Electronics and Communication Engineering

EC 010 701—VLSI DESIGN (EC)

(New Scheme-2010 Admission onwards)

[Improvement/Supplementary]

Time: Three Hours

Maximum: 100 Marks

Part A

Answer all questions.
Each question carries 3 marks.

- 1. List the process steps used in IC fabrication.
- 2. List the difference between PMOS and NMOS.
- 3. Draw the stick diagram for NOT gate.
- 4. Draw the Bi-CMOS layout structure.
- 5. List the difference between ASIC vs. FPGA.

 $(5 \times 3 = 15 \text{ marks})$

Part B

Answer all questions.
Each question carries 5 marks.

- 6. Write a note on chemical vapour deposition.
- 7. Describe Junction isolation and Dielectric isolation.
- 8. With neat CMOS structure explain latch up in CMOS.
- 9. Realize the following Boolean equation using transmission gates: f = ab + abc.
- 10. Design NOR gate using CMOS technique and draw the stick diagram for the same.

 $(5 \times 5 = 25 \text{ marks})$

Part C

Answer all questions.

Each question carries 12 marks.

11. With neat diagram, explain X-ray lithography.

Or

12. Elaborate with each and every steps of NMOS IC fabrication flow.

Turn over

13. Explain monolithic diodes and Schottky diodes with neat figure.

Or

- 14. Describe NMOS enhancement mode operation along with its characteristic curve.
- 15. With neat figure, explain each and every fabrication steps of CMOS Technology.

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- 16. Design and explain NOR-4-bit shifter.
- 17. With neat figure, explain CMOS sequential SR flip-flop and JK flip-flop.

Or

- 18. Discuss about BiCMOS Technology.
- 19. Describe about GaAs fabrication Technology.

Or

- 20. Write a short note on:
 - (a) PLA.
 - (b) FPGA.

 $(5 \times 12 = 60 \text{ marks})$